

		SPECIF	CATIONS			
CUSTO	OMER	:				
SAMPI	E CODE (Ver.)	:				
MASS	PRODUCTION CO	DE (Ver.)	PC1601ARU	LWB-A-Q	(Ver.A)	
DRAW		:	PC-95018			
		Custome	Approved			-
	Approved		-	ite:	esigner	
	Approved	QC Co	Da		esigner	-0)
* 7	pproval For Specifications This specification is subject Please contact Powertip o	Only. t to change without r it's representative	notice.	D 李y	A. 8/14	
* 7	pproval For Specifications Please contact Powertip of pproval For Specifications	Only. t to change without r it's representative and Sample.	notice. before designing you	D	A. 8/14	
- * - Ar	pproval For Specifications Please contact Powertip of pproval For Specifications	Only. t to change without r it's representative and Sample. POWERTIP	notice.	D	A. 8/14	
* 7	pproval For Specifications Please contact Powertip of pproval For Specifications	Only. t to change without r it's representative and Sample. POWERTIP Industrial Park,	notice. before designing you	D D D U U U U U U U U U U U U U	A. 8/14	ation.
Ap	pproval For Specifications This specification is subject Please contact Powertip of pproval For Specifications 5: No.8, 6 th Road, Taichung Taichung, Taiwan	Only. t to change without r it's representative and Sample. POWERTIP g Industrial Park, 8 號	notice. before designing you TECH. CORF TEL: 886-4-2355-6	D D D U U U U U U U U U U U U U	ed on this specific	cation.



2006/03/28	0	PC1601ARU-LWB-A-Q is the ROHS compliant part number based on Powertip's standard PC1601ARU-LWB-A	
2007/8/14	A	Update Timing Characteristics and Display Command	11,13

Total: 20Page



Contents

1. SPECIFICATIONS

- **1.1 Features**
- **1.2 Mechanical Specifications**
- **1.3 Absolute Maximum Ratings**
- **1.4 DC Electrical Characteristics**
- **1.5 Optical Characteristics**

2. MODULE STRUCTURE

- 2.1 Counter Drawing
- 2.2 Interface Pin Description
- 2.3 Timing Characteristics
- 2.4 Display Command
- 2.5 Character Pattern

3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart
- **3.2 Inspection Specification**

4. RELIABILITY TEST

4.1 Reliability Test Condition

5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

6. THIS PRODUCT CONFORMS THE ROHS OF PTC.

Note : For detailed information please refer to IC data sheet : <u>ST7066U</u>

1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	16*1 Characters
LCD Type	STN, YG, Positive, Reflective, Normal Temp.
Driver Condition	LCD Module : 1/16 Duty, 1/4 Bias
Viewing Direction	6 O'clock
Backlight	-
Weight	-
Interface	_

1.2 Mechanical Specifications

Item	Standard Value				
Outline Dimension	122.0 (L) * 33.0 (w) * 10.3 (H)(Max)	mm			
Viewing Area	99.0 (L) * 13.0 (w)	mm			
Active Area	94.84 (L) * 9.66 (w)	mm			
Dot Size	0.92 (L) * 1.1 (w)	mm			
Dot Pitch	0.98 (L) * 1.16 (w)	mm			

Note : For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V_{DD}	_	-0.3	7.0	V
LCD Driver Supply Voltage	V _{LCD}	—	VDD-10.0	V _{DD} +0.3	V
Input Voltage	V_{IN}	—	-0.3	V _{DD} +0.3	V
Operating Temperature	T _{OP}	Excluded B/L	0	50	°C
Storage Temperature	T _{ST}	Excluded B/L	-20	70	°C
Storage Humidity	H _D	_	—	90	%RH



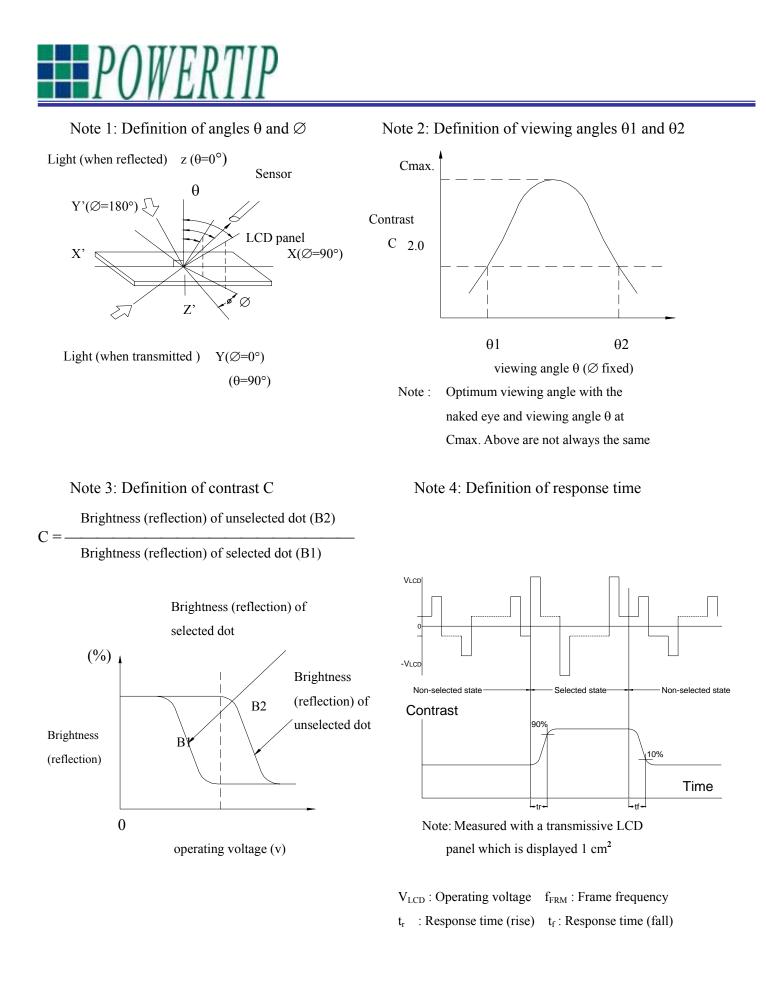
1.4 DC Electrical Characteristics

$V_{DD} = 5.0 V \pm 10\%$, $V_{SS} = 0V$, T							
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Logic Supply Voltage	V_{DD}	_	4.5	5.0	5.5	V	
"H" Input Voltage	V _{IH}	_	0.7 Vdd	-	Vdd	V	
"L" Input Voltage	V _{IL}	—	-0.3	-	0.6	V	
"H" Output Voltage	V _{OH}	IOH=-0.1mA	3.9	-	Vdd	V	
"L" Output Voltage	V _{OL}	IOL=0.1mA	-	-	0.4	V	
Supply Current	I _{DD}	$V_{DD} = 5.0 V$	-	2.0	3.0	mA	
		0°C	-	-	-		
LCM Driver Voltage	V _{OP}	25°C *1	3.8	4.0	4.2	V	
		50°C	-	_	-		

Note: *1. THE V_{OP} TEST POINT IS V_{DD} - V_O .

1.5 Optical Characteristics

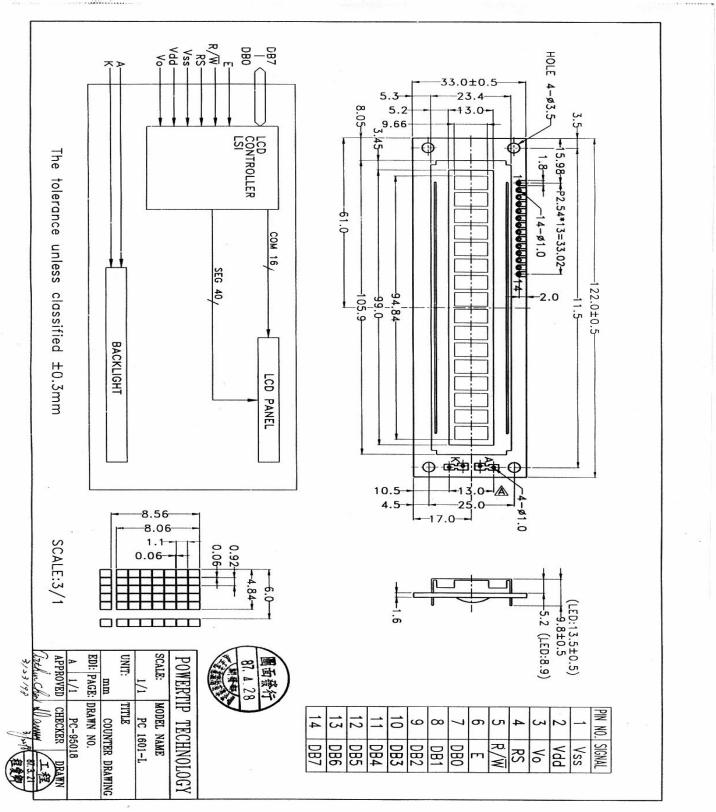
Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	θ	$C \ge 2.0, \emptyset = 0^{\circ}$	0	-	40°	Notes 1 & 2
Contrast Ratio	С	$\theta = 5^{\circ}, \emptyset = 0^{\circ}$	5	7	-	Note 3
Response Time(rise)	tr	$\theta = 5^{\circ}, \emptyset = 0^{\circ}$	-	150 ms	-	Note 4
Response Time(fall)	tf	$\theta = 5^{\circ}, \emptyset = 0^{\circ}$	-	300 ms	-	Note 4





2. MODULE STRUCTURE

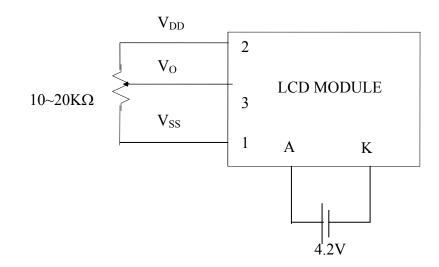
2.1 Counter Drawing



2.2 Interface Pin Description

Pin No.	Symbol	Signal Description
1	Vss	Power Supply (V _{SS} =0)
2	VDD	Power Supply (V _{DD} >V _{SS})
3	Vo	Operating voltage (LCD Driver)
		Register Selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
5		Read/Write signal input is used to select the read/write mode
5	R/W	High = Read mode, Low = Write mode
6	Е	Start enable signal to read or write the data
		Four low order bi-directional three-state data bus lines.
7~10	DB0 ~ DB3	Used for data transfer between the MPU and the LCD
/~10		module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	$DB4 \sim DB7$	Used for data transfer between the MPU and the LCD
		module.
		DB7 can be used as a busy flag.
	А	Power supply for LED B / L (+)
	K	Power supply for LED B / L (-)

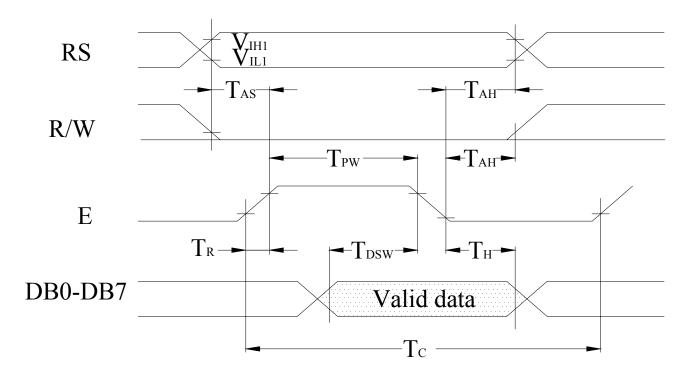
Contrast Adjust



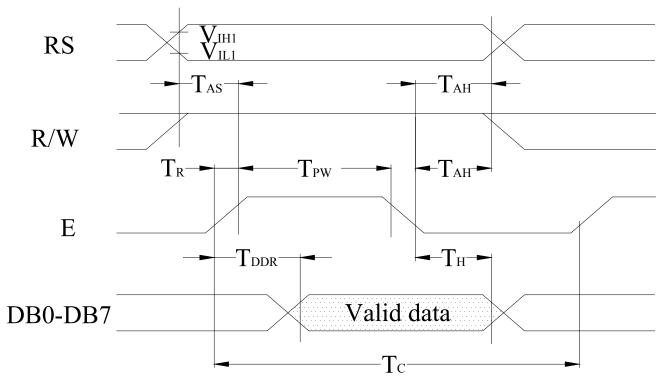


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



• Reading data from ST7066U to MPU





• Write Mode (Writing data from MPU to ST7066U)

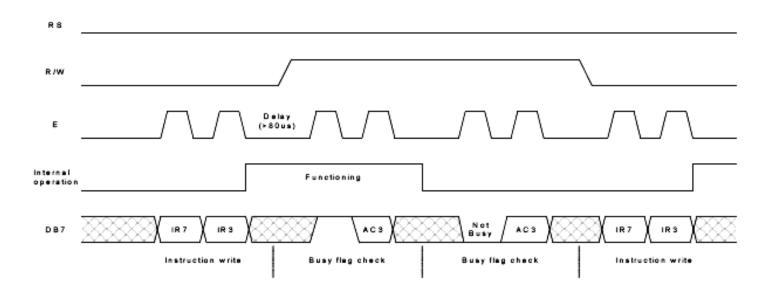
(VDD=5.0V±10%,VSS=0V,Ta=25°C) Symbol Characteristics **Test Condition** Unit Min. Max. Typ. Pin E T_{C} Enable Cycle Time 1200 _ _ ns Enable Pulse Width Pin E 140 T_{PW} -ns T_R , T_F Enable Rise / Fall Time Pin E 25 ns -Address Setup Time Pins: RS, RW,E T_{AS} 0 _ _ ns Pins :RS,RW,E T_{AH} Address Hold Time 10 -ns Data Setup Time Pins:DB0~DB7 40 T_{DSW} ns --Data Hold Time Pins:DB0~DB7 T_{H} 10 _ _ ns

• Read Mode (Reading data from ST7066U to MPU)

(VDD=5.0V±10%,VSS=0V,Ta=25°C)

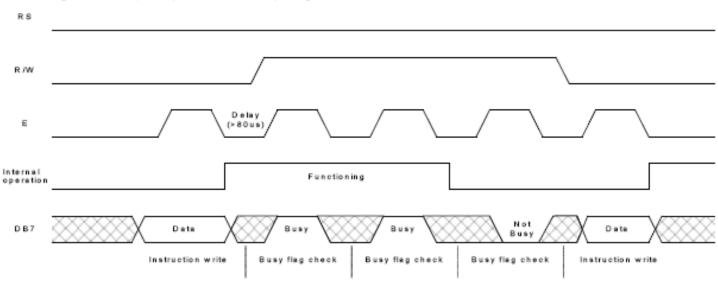
			(====;
Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T_{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T _{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
$T_{\rm H}$	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

For 4-bit interface date, only four bus lines (DB4 to DB7) are used for transfer.



Example of busy flag check timing sequence

For 8-bit interface date, all eight bus lines (DB0 to DB7) are used .



Example of busy flag check timing sequence

2.4 Display Command

		Instruction Code										Description
Instructions	RS	R/W	DB 7	DB 6	DB 5	DB 4	DB 3	DB 2	DB 1	DB 0	Description	Time (270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC.	1.52ms
Return Home	0	0	0	0	0	0	0	0	1	×	Set DDRAM address to "00H" from AC and return cursor to it's original position if shifted. The contents of DDRAM are not changed.	1.52ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37118
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1 : entire display on C=1 : cursor on B=1 : cursor position on	37µs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	×	×	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	37µs
Function Set	0	0	0	0	1	DL	N	F	×	×	DL: interface data is 8/4 bits NL: number of line is 2/1 F: font size is 5×11/5×8	37µs
Set CGRAM Address	0	0	0	1	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set CGRAM address in address counter.	37µs
Set DDRAM Address	0	0	1	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set DDRAM address in address counter.	37µs



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0µs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	37µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	37µs

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Before checking BF, be sure to wait at least 80us.. Do not keep "E" always "High" for checking BF. Refer to Instruction Table for the list of each instruction execution time .

2.5 Character Pattern

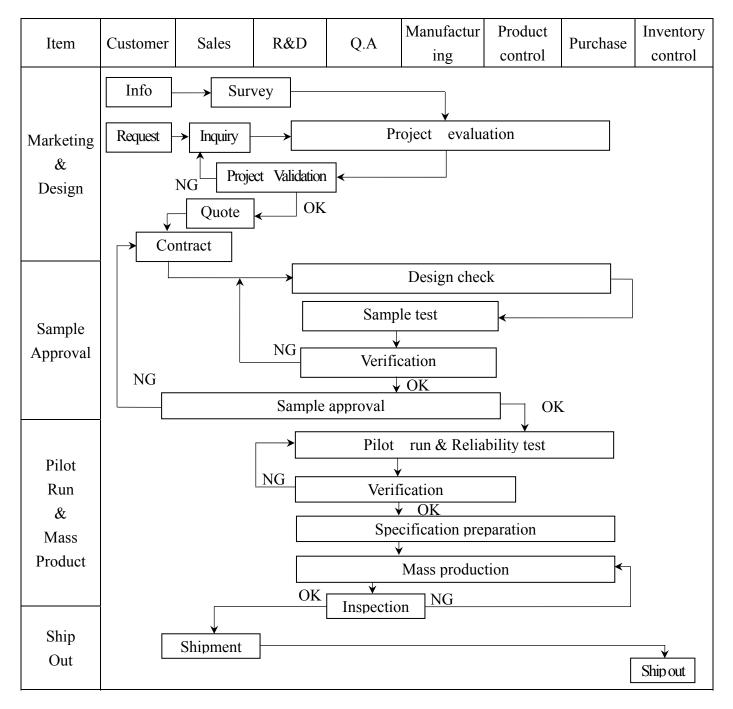
CHARACTER PATTERN(EB,WB)

		ŀ	ligh	4-b	oit (C)4to	D7) of (Cha	ract	er C	ode) (H	exa	deci	ma)
		0	1	2	3	4	5	6	7	8	9	A	в	С	D	E	F
	0	CG RAM (1)	<u></u>		Ø	(B	F	•:	₽≕•	۲ <u></u>	Ē		-	Ļ		[],	.
	1	CG RAM (2)	===	!	1	P	0		-::-]	·	3B	Í	••	J.		` ?'`	Ŀ.>
	2	CG RAM (3)	5			E	R	Ŀ>	ŀ	÷	F	÷	-:-		÷	-3	3
-	3	CG RAM (4)	Ľ.	#		[]]:	:;	:	: .	.	<u>.</u>			[]."	47		÷
decima	4	CG RAM (5)	ľ	:#:	::].	D	T		Ŧ			4		- <u>-</u> I	[]]]		\odot
(Hexa	5	CG RAM (6)	١			<u></u>	II		I]		<u>.</u>	£	13	·†·	2	ï	.ih.
er Code	6	CG RAM (7)	 	8.	≞.	!	IJ	Ŧ	ıı	. .	Ċ.	4	I 1.j		⊞	₿	j
4-bit (D0 to D3) of Character Code (Hexadecimal)	7	CG RAM (8)			i."	G	Į, J		<u>.</u> .,	.	Ċ.	Fi.	:»:	j-	÷,	I	11]
3) of CI	8	CG RAM (1)		Ć	8		×	ŀ'n	\approx	÷	Ċ.	F	-÷	- E	 	ŀ	IP:
D0 to D	9	CG RAM (2)	·. I)	9	Ι	ı,ı	1	' <u></u> l	÷	<u>.</u>	i	<u>.</u>	[Π	З.	-:-
	A	CG RAM (3)	:::	:4:	::	J	2	j.	2	è	ij	ä			2	μ. ι.	
Lower	в	CG RAM (4)			;;	k€	Е	k:	÷	ï	ř.	3	-#:	I	ſ.	Ļ.?	-1
	С	CG RAM (5)		:*	<	I	••••	1	I	ż	P	3	≫]	Φ	2	
	D	CG RAM (6)	ů,			ŀſ]	rn]}	ì.	-==	8	:p!:		I.H.I	T	
	Е	CG RAM (7)	2			ŀ·ŀ		ŀ"ı	··	iii i	\square	Ø	·.["	Ø	52	P	
	F	CG RAM (8)	3					c	<u>.</u>	jä,	<u>.</u>	s		œ	C	ŗŢ	



3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart





Item	Customer	Sales	R&D	Q.A	Manufactu ring	Product control	Purchase	Inventory control
Sales Service	Info	Claim	[Trackin	Failure an Corrective			
Q.A Activity	 ISO 9001 Equipment Standardi 		n		ocess improv ducation An			



3.2 Inspection Specification

Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level II • Equipment : Gauge • MIL-STD • Powertip Tester • Sample •

IQC Defect Level : Major Defect AQL 0.4; Minor Defect AQL 1.5 •

FQC Defect Level : 100% Inspection •

OUT Going Defect Level : Sampling \circ

Specification :

NO	Item	Specification	Judge	Level
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major
	Electronic	The display lacks of some patterns.	N.G.	Major
	characteristics of LCM A=(L+W)÷2	8		Major
3		The size of missing dot, A is $> 1/2$ Dot size	N.G.	Major
		There is no function.	N.G.	Major
	· · · ·	Output data is error	N.G.	Major
		Material is different with work order of production	N.G.	Major
		LCD is assembled in inverse direction	N.G.	Major
		Bezel is assembled in inverse direction	N.G.	Major
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major
	Appearance of	The diameter of dirty particle, A is >0.4 mm	N.G.	Minor
	LCD A=(L + W)÷2	Dirty particle length is $>$ 3.0mm, and 0.01mm $<$ width \leq 0.05mm	N.G.	Minor
4	Dirty particle (Including scratch bubble)	Display is without protective film	N.G.	Minor
		Conductive rubber is over bezel 1mm	N.G.	Minor
		Polarizer exceeds over viewing area of LCD	N.G.	Minor
		Area of bubble in polarizer, $A > 1.0$ mm, the number of		
		bubble is >1 piece.	N.G.	Minor
		0.4mm < Area of bubble in polarizer, A < 1.0mm, the number of bubble is >4 pieces.	N.G.	Minor
		Burned area or wrong part number is on PCB	N.G.	Major
	Appearance of PCB A=(L + W)÷2	The symbol, character, and mark of PCB are unidentifiable.	N.G	Minor
		The stripped solder mask , A is > 1.0mm	N.G.	Minor
5		0.3 mm < stripped solder mask or visible circuit, A < 1.0mm, and the number is ≥ 4 pieces	N.G.	Minor
		There is particle between the circuits in solder mask	N.G	Minor
		The circuit is peeled off or cracked	N.G	Minor
		There is any circuits risen or exposed.	N.G	Minor
		0.2mm < Area of solder ball, A is ≤ 0.4 mm The number of solder ball is ≥ 3 pieces	N.G	Minor
		The magnitude of solder ball, A is >0.4 mm.	N.G	Minor

NO	Item	Specification	Judge	Level
6		The shape of modeling is deformed by touching.	N.G.	Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
	molding $A=(L+W)\div 2$	Excessive epoxy: Diameter of modeling is >20 mm or height is >2.5 mm	N.G.	Minor
		The diameter of pinhole in modeling, A is >0.2 mm.	N.G.	Minor
		The folding angle of frame must be $>45^{\circ} +10^{\circ}$	N.G.	Minor
-	Appearance of frame	The area of stripped electroplate in top-view of frame, A is > 1.0 mm.	N.G.	Minor
7	A=(L+W)÷2	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is >0.06 mm. (Top view only)	N.G.	Minor
	Γ_1 - trian	The color of backlight is nonconforming	N.G.	Major
	Electrical characteristic of	Backlight can't work normally.	N.G.	Major
8	backlight	The LED lamp can't work normally	N.G.	Major
8	$A=(L+W)\div 2$	The unsoldering area of pin for backlight, A is $> 1/2$ solder joint area.	N.G.	Minor
	$\Pi (\mathbf{L} + \mathbf{W}) \cdot \mathbf{Z}$	The height of solder pin for backlight is >2.0 mm	N.G.	Minor
	Assembly parts A=(L+W)÷2	The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and surface of the PCB is floating >0.7 mm	N.G.	Minor
10		D > 1/4W W $D\downarrow \downarrow \downarrow\downarrow \downarrow \downarrowD'$ Pad	N.G.	Minor
		End solder joint width, D' is $>50\%$ width of component termination or width of pad	N.G.	Minor
		Side overhang, D is $>25\%$ width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is <0.5 mm.	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Co	ndition			
1	High Temperature Storage	Storage at 70 $\pm 2^{\circ}$ C 96~100 hrs Surrounding temperature, then stored thrs	rage at normal condition			
2	Low Temperature Storage	Storage at -20 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs				
3	High Temperature /Humidity Storage	 1.Storage 96~100 hrs 60±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4 hrs. 				
4	Temperature Cycling	$-20^{\circ}C \rightarrow 25^{\circ}C \rightarrow 70^{\circ}C \rightarrow 25^{\circ}C$ $(30 \text{mins}) (5 \text{mins}) (30 \text{mins}) (5 \text{mins})$ 10 Cycle				
5	Vibration	10~55Hz (1 minute) 1.5mm X,Y and Z direction * (each 2hrs)				
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.			
7	Drop Test	Packing Weight (Kg) 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454	Drop Height (cm) 122 76 61 46			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320\pm10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM .

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.